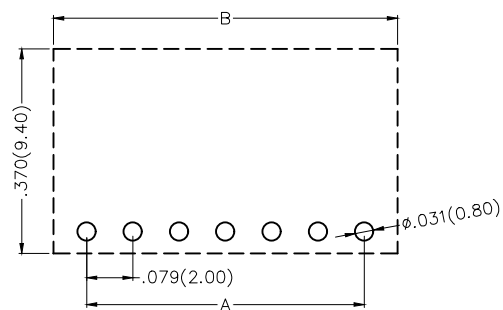
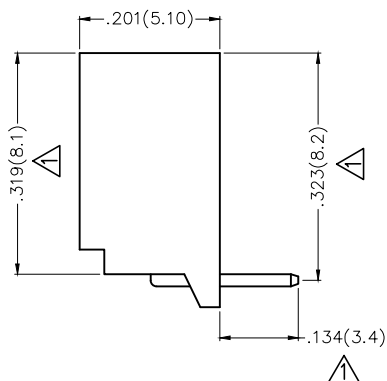
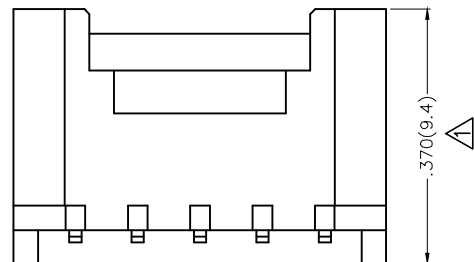
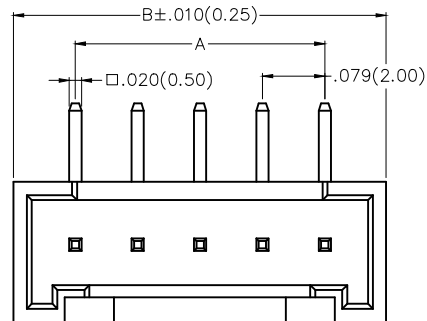




Recommended P.C.Board Layout

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Dimension: Change 9.25 into 9.4mm, Change 7.80 into 8.1mm, Change 7.95 into 8.2mm, Change 3.20 into 3.4mm.	17/OCT/18	KATE	FRANK

Electrical

Current Rating: 2.0A AC(rms)/DC
Voltage Rating: 125V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 800V AC r.m.s
Temperature Range—Operating: -25°C~+85°C

Material and Plating

Housing: PA66(UL 94V-0)
Contact Pin: Brass
Plating: Tin Plated

Ordering Information

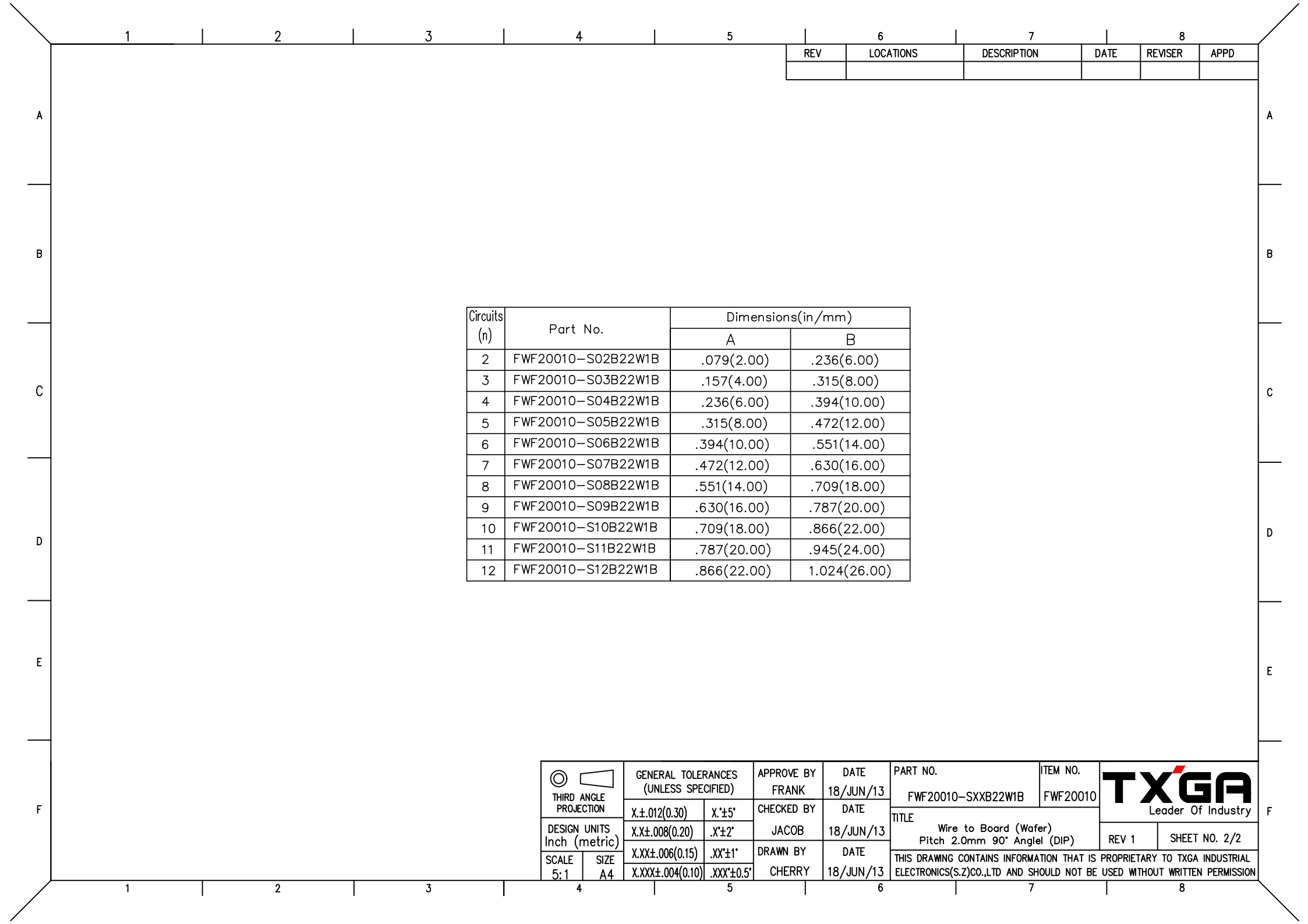
FWF 200 10 — S XX B 2 2 W1 B
1 2 3 4 5 6 7 8 9 10

1 Category FWF—Wafer	2 Series Number 200—Pitch2.0mm	3 Distinction No. 10	4 Row Option Single Row	5 Circuits XX	6 Entry Angle B—90° Angle
7 Plating 2—Tin Plated	8 Material—Resin 2—PA66	9 Color—Resin W1—White	10 Packaging B—PE Bag		

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF20010—SXXB22W1B	ITEM NO. FWF20010	 Leader Of Industry	
DESIGN UNITS Inch (metric)		X.±.012(0.30)	X'.±5'	CHECKED BY	DATE	TITLE			
		X.X±.008(0.20)	X'.±2'	JACOB	18/JUN/13	Wire to Board (Wafer) Pitch 2.0mm 90° Anglet (DIP)			
SCALE 5:1		SIZE A4		DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				CHERRY	18/JUN/13				
		X.XXX±.004(0.10)	XXX'.±0.5'			REV 1		SHEET NO. 1/2	

TXGA
Leader Of Industry

REV 1 SHEET NO. 1/2



REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF20010-S02B22W1B	.079(2.00)	.236(6.00)
3	FWF20010-S03B22W1B	.157(4.00)	.315(8.00)
4	FWF20010-S04B22W1B	.236(6.00)	.394(10.00)
5	FWF20010-S05B22W1B	.315(8.00)	.472(12.00)
6	FWF20010-S06B22W1B	.394(10.00)	.551(14.00)
7	FWF20010-S07B22W1B	.472(12.00)	.630(16.00)
8	FWF20010-S08B22W1B	.551(14.00)	.709(18.00)
9	FWF20010-S09B22W1B	.630(16.00)	.787(20.00)
10	FWF20010-S10B22W1B	.709(18.00)	.866(22.00)
11	FWF20010-S11B22W1B	.787(20.00)	.945(24.00)
12	FWF20010-S12B22W1B	.866(22.00)	1.024(26.00)

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 18/JUN/13	PART NO. FWF20010-SXXB22W1B	ITEM NO. FWF20010	 Leader Of Industry	
		X.±.012(0.30)	X'.±5'	CHECKED BY JACOB	DATE 18/JUN/13	TITLE Wire to Board (Wafer) Pitch 2.0mm 90° Anglge (DIP)			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	X'.±2'	DRAWN BY CHERRY	DATE 18/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		X.XX±.006(0.15)	.XX'±1'						
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX'±0.5'					REV 1	SHEET NO. 2/2